











SNAS711A - OCTOBER 2016-REVISED JANUARY 2017

LMX2491

LMX2491 6.4-GHz Low Noise RF PLL With Ramp/Chirp Generation

Features

- -227-dBc/Hz Normalized PLL Noise
- 500-MHz to 6.4-GHz Wideband PLL
- 3.15-V to 5.25-V Charge Pump PLL Supply
- Versatile Ramp / Chirp Generation
- 200-MHz Maximum Phase Detector Frequency
- FSK / PSK Modulation Pin
- **Digital Lock Detect**
- Single 3.3-V Supply Capability

Applications

- **FMCW Radars**
- Military Radars
- Microwave Backhaul
- **Test and Measurement**
- Satellite Communications
- Wireless Infrastructure
- Sampling Clock for High-Speed ADC/DAC

3 Description

The LMX2491 device is a low-noise, 6.4-GHz wideband delta-sigma fractional N PLL with ramp and chirp generation. It consists of a phase frequency detector, programmable charge pump, and high frequency input for the external VCO. The LMX2491 supports a broad and flexible class of ramping capabilities, including FSK, PSK, and configurable piecewise linear FM modulation profiles of up to 8 segments. It supports fine PLL resolution and fast ramp with up to a 200-MHz phase detector rate. The LMX2491 allows any of its registers to be read back. The LMX2491 can operate with a single 3.3-V supply. Moreover, supporting up to 5.25-V charge pump can eliminate the need of external amplifier, leading to a simpler solution with improved phase noise performance.

Device Information

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LMX2491	WQFN (24)	4.00 mm × 4.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Schematic

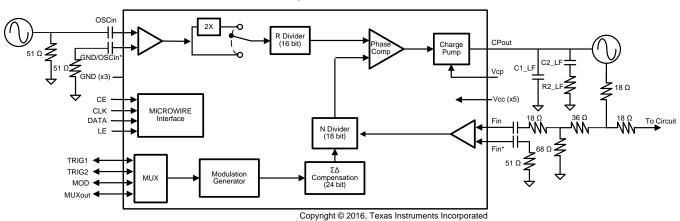




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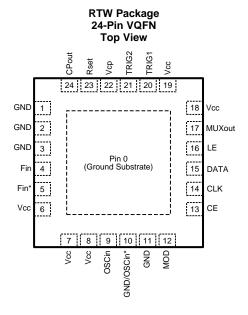
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4 Revision History

CI	hanges from Original (October 2016) to Revision A	Page
•	Deleted Charge pump output pin from the table	4
•	Changed to Supply voltage	4
•	Changed to I/O input voltage	
•	Changed to Power down current	5
•	Changed DATA field bit description	6
•	Added new plots in Typical Characteristics	<mark>7</mark>
•	Changed Table 1 title	9
•	Added CMP0 and CMP1 definition. Changed Equation 1 description.	12
•	Added Register Readback	13
•	Added MSB bit description	
•	Changed the format in Window and fpD Frequency column	21
•	Changed to correct register bits location	
•	Changed to correct value	25
•	Added correct start time	26
•	Added design details and plots in Typical Application	27



5 Pin Configuration and Functions



Pin Functions

TEF	RMINAL	TVDE	DESCRIPTION	
NO.	NAME	TYPE	DESCRIPTION	
0	DAP	GND	Die Attach Pad. Connect to PCB ground plane.	
1	GND	GND	ound for charge pump.	
2, 3	GND	GND	round for Fin Buffer	
4, 5	Fin Fin*	Input	Complimentary high frequency input pins. Should be AC-coupled. If driving single-ended, impedance as seen from Fin and Fin* pins looking outwards from the part should be roughly the same.	
6	Vcc	Supply	Power Supply for Fin Buffer	
7	Vcc	Supply	Supply for On-chip LDOs	
8	Vcc	Supply	Supply for OSCin Buffer	
9	OSCin	Input	Reference Frequency Input	
10	GND/ OSCin*	GND/Input	Complimentary input for OSCin. If not used, it is recommended to match the termination as seen from the OSCin terminal looking outwards. However, this may also be grounded as well.	
11	GND	GND	Ground for OSCin Buffer	
12	MOD	Input/Output	Multiplexed Input/Output Pins for Ramp Triggers, FSK/PSK Modulation, FastLock, and Diagnostics	
13	CE	Input	Chip Enable	
14	CLK	GND	Serial Programming Clock.	
15	DATA	GND	Serial Programming Data	
16	LE	Input	Serial Programming Latch Enable	
17	MUXout	Input/Output	Multiplexed Input/Output Pins for Ramp Triggers, FSK/PSK Modulation, FastLock, and Diagnostics	
18	Vcc	Supply	Supply for delta sigma engine.	
19	Vcc	Supply	upply for general circuitry.	
20	TRIG1	Input/Output	Multiplexed Input/Output Pins for Ramp Triggers, FSK/PSK Modulation, FastLock, and Diagnostics	
21	TRIG2	Input/Output	Multiplexed Input/Output Pins for Ramp Triggers, FSK/PSK Modulation, FastLock, and Diagnostics	
22	Vcp	Supply	Power Supply for the charge pump.	
23	Rset	NC	No connect.	
24	CPout	Output	Charge Pump Output	



6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
V_{CP}	Supply voltage for charge pump	V _{CC}	5.5	V
V _{CC}	Supply voltage	-0.3	3.6	V
V _{IN}	I/O input voltage	-0.3	$V_{CC} + 0.3$	V
T _{Solder}	Lead temperature (solder 4 seconds)		260	°C
T _{Junction}	Junction temperature		150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 Storage Conditions

applicable before the DMD is installed in the final product

		MIN	MAX	UNIT
T _{stg}	DMD storage temperature	-65	150	°C
T_{DP}	Storage dew point		3	°C

6.3 ESD Ratings

			VALUE	UNIT
V	Floatroctatio discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2500	\/
V _(ESD)	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±1500	V

¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	3.15	3.3	3.45	V
V_{CP}	Charge pump supply voltage	V_{CC}		5.25	V
T _A	Ambient temperature	-40		85	°C
T_{J}	Junction temperature	-40		125	°C

6.5 Thermal Information

	THERMAL METRIC ⁽¹⁾	RTW (VQFN)	UNIT
		24 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	39.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	7.1	°C/W
ΨЈВ	Junction-to-board characterization parameter	20	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



6.6 Electrical Characteristics

 $3.15~\text{V} \leq \text{V}_{\text{CC}} \leq 3.45~\text{V},~\text{V}_{\text{CC}} \leq \text{V}_{\text{CP}} \leq 5.25~\text{V},~-40~\text{°C} \leq \text{T}_{\text{A}} \leq 85~\text{°C},~\text{except as specified}.~\text{Typical values are at V}_{\text{CC}} = \text{V}_{\text{CP}} = 3.3~\text{V},~\text{V}_{\text{CC}} \leq \text{V}_{\text{CP}} \leq 5.25~\text{V},~\text{C}_{\text{CP}} \leq 5.25~\text{C}_{\text{CP}} \leq 5.25~\text{V},~\text{C}_{\text{CP}} \leq 5.25~\text{C}_{\text{CP}} \leq 5.25~\text{C}_{\text{CP$

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
			f _{PD} = 10 MHz		45		
	Current consumption	All Vcc pins	f _{PD} = 100 MHz		50		mA
			f _{PD} = 200 MHz		55		
I _{CC}			$K_{PD} = 0.1 \text{ mA}$		2		
		Vcp pin	K _{PD} = 1.6 mA		10		
			K _{PD} = 3.1 mA		19		
I _{CC} PD	Power down current	POWERDOWN			3		
		OSC_DIFFR = 0	doubler disabled	10		600	
	Frequency for OSCin	OSC_DIFFR = 0	doubler enabled	10		300	N 41 1-
f _{OSCin}	terminal	OSC_DIFFR = 1,	doubler disabled	10		1200	MHz
		OSC_DIFFR = 1,	doubler enabled	10		600	
V _{OSCin}	Voltage for OSCin pin ⁽¹⁾			0.5		V _{CC} - 0.5	V_{PP}
f _{Fin}	Frequency for Fin pin			500		6400	MHz
P _{Fin}	Power for Fin pin	Single-ended ope	eration	-5		5	dBm
f _{PD}	Phase detector frequency					200	MHz
PN1Hz	PLL figure of merit ⁽²⁾				-227		dBc/Hz
PN10kHz	Normalized PLL 1/f noise ⁽²⁾	Normalized to 10 GHz carrier.	Normalized to 10-kHz offset for a 1-GHz carrier.		-120		dBc/Hz
I _{CPout} TRI	Charge pump leakage tri- state leakage					10	nA
I _{CPout} MM	Charge pump mismatch (3)	V _{CPout} = V _{CP} / 2			5%		
			CPG = 1X		0.1		
I _{CPout}	Charge pump current	$V_{CPout} = V_{CP} / 2$					mA
			CPG = 31X		3.1		
LOGIC OU	TPUT TERMINALS (MUXout,	TRIG1, TRIG2, MO	OD)				
V _{OH}	Output high voltage			$0.8 \times V_{CC}$	V_{CC}		V
V_{OL}	Output low voltage				0	$0.2 \times V_{CC}$	V
LOGIC INP	UT TERMINALS (CE, CLK, DA	ATA, LE, MUXout	TRIG1, TRIG2, MC	D)			
V_{IH}	Input high voltage			1.4		V _{CC}	V
V _{IL}	Input low voltage			0		0.6	V
I _{IH}	Input leakage current			- 5	1	5	μΑ
t _{CE} LOW	Chip enable low time			5			μs
t _{CE} HIGH	Chip enable high time			5			μs

⁽¹⁾ For optimal phase noise performance, higher input voltage and a slew rate of at least 3 V/ns is recommended

⁽²⁾ PLL Noise Metrics are measured with a clean OSCin signal with a high slew rate using a wide loop bandwidth. The noise metrics model the PLL noise for an infinite loop bandwidth as:

PLL_Total = 10 × log(10^{PLL_Flat / 10} + 10^{PLL_Flicker(Offset) / 10})

PLL_Flat = PN1Hz + 20 × log(N) + 10 × log(f_{PD} / 1 Hz)

PLL_Flicker = PN10kHz - 10 × log(Offset / 10 kHz) + 20 × log(f_{VCO} / 1 GHz)

(3) Charge pump mismatch varies as a function of charge pump voltage. Consult typical performance characteristics to see this variation.



6.7 Timing Requirements, Programming Interface (CLK, DATA, LE)

		MIN	TYP	MAX	UNIT
t _{CE}	Clock to LE low time	10			ns
t _{CS}	Data to clock setup time	4			ns
t _{CH}	Data to clock hold time	4			ns
t _{CWH}	Clock pulse width high	10			ns
t _{CWL}	Clock pulse width low	10			ns
t _{CES}	Enable to clock setup time	10			ns
t _{EWH}	Enable pulse width high	10			ns

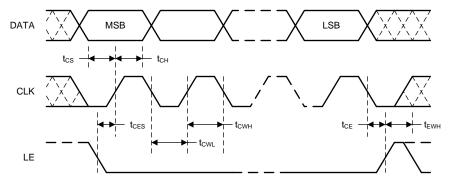
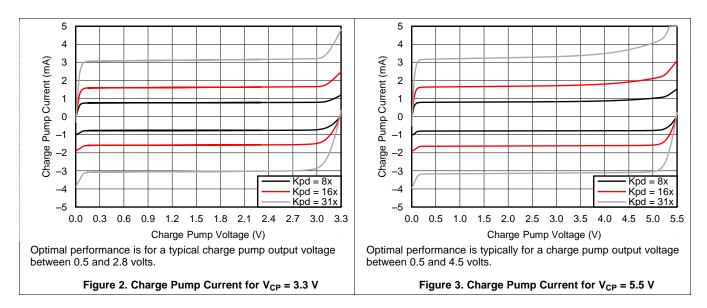


Figure 1. Serial Data Input Timing

There are several other considerations for programming:

- The DATA is clocked into a shift register on each rising edge of the CLK signal. On the rising edge of the LE signal, the data is sent from the shift register to an actual counter.
- If no LE signal is given after the last data bit and the clock is kept toggling, then these bits are read into the next lower register. This eliminates the need to send the address each time.
- A slew rate of at least 30 V/µs is recommended for the CLK, DATA, and LE signals
- Timing specs also apply to readback. Readback can be done through the MUXout, TRIG1, TRIG2, or MOD terminals.

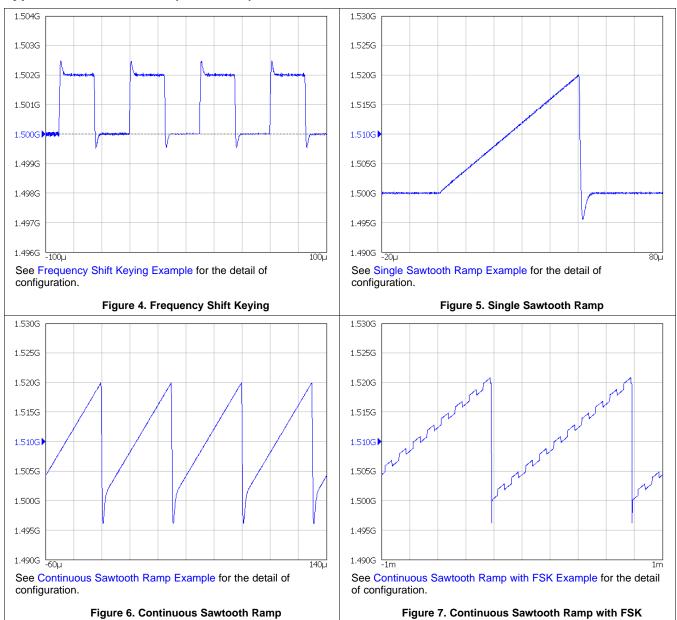
6.8 Typical Characteristics



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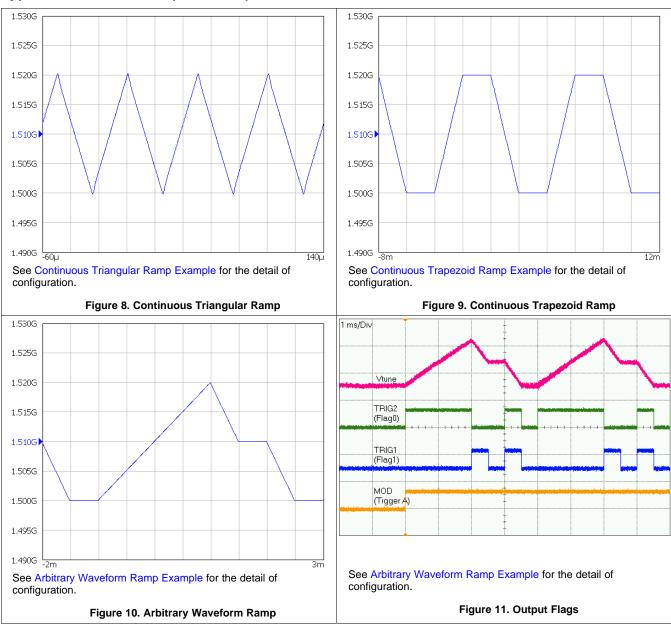
Typical Characteristics (continued)



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Typical Characteristics (continued)



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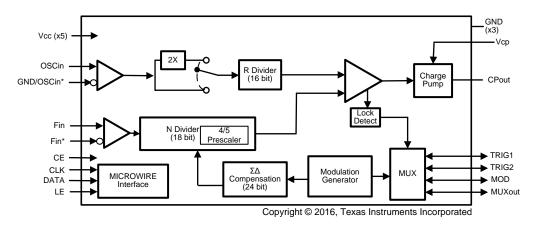


7 Detailed Description

7.1 Overview

The LMX2491 is a microwave PLL, consisting of a reference input and divider, high frequency input and divider, charge pump, ramp generator, and other digital logic. The Vcc power supply pins run at a nominal 3.3 volts, while the charge pump supply pin, Vcp, operates anywhere from V_{CC} to 5 volts. The device is designed to operate with an external loop filter and VCO. Modulation is achieved by manipulating the MASH engine.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 OSCin Input

The reference can be applied in several ways. If using a differential input, this must be terminated differentially with a $100-\Omega$ resistance and AC-coupled to the OSCin and GND/OSCin* terminals. If driving this single-ended, then the GND/OSCin* terminal may be grounded, although better performance is attained by connecting the GND/OSCin* terminal through a series resistance and capacitance to ground to match the OSCin terminal impedance.

7.3.2 OSCin Doubler

The OSCin doubler allows the input signal to the OSCin to be doubled to have higher phase detector frequencies. This works by clocking on both the rising and falling edges of the input signal, so it therefore requires a 50% input duty cycle.

7.3.3 R Divider

The R counter is 16 bits divides the OSCin signal from 1 to 65535. If DIFF_R = 0, then any value can be chosen in this range. If DIFF_R = 1, then the divide is restricted to 2, 4, 8, and 16, but allows for higher OSCin frequencies.

7.3.4 PLL N Divider

The 16-bit N divider divides the signal at the Fin terminal down to the phase detector frequency. It contains a 4/5 prescaler that creates minimum divide restrictions, but allows the N value to increment in values of one.

Table 1. Allowable Minimum N Divider Values

MODULATOR ORDER	MINIMUM N DIVIDE
Integer Mode, 1st-Order Modulator	16
2nd-Order Modulator	17
3rd-Order Modulator	19
4th-Order Modulator	25



7.3.5 Fractional Circuitry

The fractional circuitry controls the N divider with delta sigma modulation that supports a programmable first, second, third, and fourth-order modulator. The fractional denominator is a fully programmable 24-bit denominator that can support any value from 1, 2, ..., 2^{24} , with the exception when the device is running one of the ramps, and in this case it is a fixed size of 2^{24} .

7.3.6 PLL Phase Detector and Charge Pump

The phase detector compares the outputs of the R and N dividers and generates a correction voltage corresponding to the phase error. This voltage is converted to a correction current by the charge pump. The phase detector frequency, f_{PD} , can be calculated as follows: $f_{PD} = f_{OSC_{in}} \times OSC_{2X} / R$.

The charge pump supply voltage on this device, V_{CP} , can be either run at the V_{CC} voltage, or up to 5.25 volts to get higher tuning voltages to present to the VCO.

7.3.7 External Loop Filter

The loop filter is external to the device and is application specific. Texas Instruments website has details on this at www.ti.com.

7.3.8 Fastlock and Cycle Slip Reduction

This PLL has a Fastlock and a cycle slipping reduction feature. The user can enable these two features by programming FL_TOC to a non-zero value. Every time PLL_N (the feedback divider, register R17 and R16) is written, the Fastlock feature engages for the prescribed time set in FL_TOC. There are 3 actions that can be enabled while the counter is running:

- 1. Change the charge pump current to the desired higher value FL_CPG. Typically this value would be set to the maximum at 31x. This increases the loop bandwidth and hence reduces lock time.
- 2. Change the phase detector frequency with FL_CSR to reduce cycle slipping. The phase detector frequency can be reduced by a factor 2 or 4 to reduce cycle slipping.
- 3. The loop filter can be configured to have a switchable R2 resistor to increase loop bandwidth and hence reduce lock time. A resistor R2pLF is added in parallel to R2_LF and connected to the a terminal on the PLL to use the internal switch. Any of the terminal MUXout, MOD, TRIG1,or TRIG2 can be configured for the function. The terminal configuration is set as *Output TOC Running*. Also set the terminal as *output inverted OD* (OD for open-drain) so the output will be high impedance in normal operation and act as ground in Fastlock. The suggested schematic for that feature is shown in Figure 12.

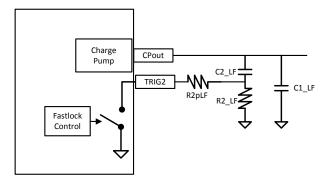


Figure 12. Suggested Schematic to Enable the Variable Loop Bandwidth Filter In Fastlock Mode

Table 2. Fastlock Settings: Charge Pump Gain and Fastlock Pin Status

PARAMETER	NORMAL OPERATION	FASTLOCK OPERATION		
Charge Pump Gain	CPG	FL_CPG		
Device Pin (TRIG1, TRIG2, MOD, or MUXout)	High Impedance	Grounded		



The resistor and the charge pump current are changed simultaneously so that the phase margin remains the same while the loop bandwidth is by a factor of K as shown in the following table:

Table 3. Suggested Equations to Calculate R2pLF

	PARAMETER	CALCULATION
FL_CPG	Charge Pump Gain in Fastlock	Typically use the highest value.
K	Loop Bandwidth Multiplier	K = sqrt(FL_CPG / CPG)
R2pLF	External Resistor	R2 / (K - 1)

Cycle slip reduction is another method that can also be used to speed up lock time by reducing cycle slipping. Cycle slipping typically occurs when the phase detector frequency exceeds about 100x the loop bandwidth of the PLL. Cycle slip reduction works in a different way than fastlock. To use this, the phase detector frequency is decreased while the charge pump current is simultaneously increased by the same factor. Although the loop bandwidth is unchanged, the ratio of the phase detector frequency to the loop bandwidth is, and this is helpful for cases when the phase detector frequency is high. Because cycle slip reduction changes the phase detector rate, it also impacts other things that are based on the phase detector rate, such as the fastlock timeout-counter and ramping controls.

7.3.9 Lock Detect and Charge Pump Voltage Monitor

The LMX2491 offers two methods to determine if the PLL is in lock: charge pump voltage monitoring and digital lock detect. These features can be used individually or in conjunction to give a reliable indication of when the PLL is in lock. The output of this detection can be routed to the TRIG1, TRIG2, MOD, or MUXout terminals.

7.3.9.1 Charge Pump Voltage Monitor

The charge pump voltage monitor allows the user to set low (CMP_THR_LOW) and high (CMP_THR_HIGH) thresholds for a comparator that monitors the charge pump output voltage.

Table 4. Desired Comparator Threshold Register Settings for Two Charge Pump Supplies

V _{CP}	THRESHOLD	SUGGESTED LEVEL
3.3 V	CPM_THR_LOW = (Vthresh + 0.08) / 0.085	6 for 0.5-V limit
3.3 V	CPM_THR_HIGH = (Vthresh - 0.96) / 0.044	42 for 2.8-V limit
50.	CPM_THR_LOW = (Vthresh + 0.056) / 0.137	4 for 0.5-V limit
5.0 V	CPM_THR_HIGH = (Vthresh -1.23) / 0.071	46 for 4.5-V limit

7.3.9.2 Digital Lock Detect

Digital lock detect works by comparing the phase error as presented to the phase detector. If the phase error plus the delay as specified by the PFD_DLY bit is outside the tolerance as specified by DLD_TOL, then this comparison would be considered to be an error, otherwise passing. The DLD_ERR_CNT specifies how may errors are necessary to cause the circuit to consider the PLL to be unlocked. The DLD_PASS_CNT specifies how many passing comparisons are necessary to cause the PLL to be considered to be locked and also resets the count for the errors. The DLD_TOL value should be set to no more than half of a phase detector period plus the PFD_DLY value. The DLD_ERR_CNT and DLD_PASS_CNT values can be decreased to make the circuit more sensitive. If the circuit is too sensitive, then chattering can occur and the DLD_ERR_CNT, DLD PASS CNT, or DLD TOL values should be increased.

NOTE

If the OSCin signal goes away and there is no noise or self-oscillation at the OSCin pin, then it is possible for the digital lock detect to indicate a locked state when the PLL really is not in lock. If this is a concern, then digital lock detect can be combined with charge pump voltage monitor to detect this situation.



7.3.10 FSK/PSK Modulation

Two-level FSK or PSK modulation can be created whenever a trigger event, as defined by the FSK_TRIG field is detected. This trigger can be defined as a transition on a terminal (TRIG1, TRIG2, MOD, or MUXout) or done purely in software. The RAMP_PM_EN bit defines the modulation to be either FSK or PSK and the FSK_DEV register determines the amount of the deviation. Remember that the FSK_DEV[32:0] field is programmed as the 2's complement of the actual desired FSK_DEV value. This modulation can be added to the modulation created from the ramping functions as well.

Table 5. How to Obtain Deviation for Two Types of Modulation

RAMP_PM_EN	MODULATION TYPE	DEVIATION
0	2 Level FSK	f _{PD} × FSK_DEV / 2 ²⁴
1	2 Level PSK	360° × FSK_DEV / 2 ²⁴

7.3.11 Ramping Functions

The LMX2491 supports a broad and flexible class of FMCW modulation formed by up to 8 linear ramps. When the ramping function is running, the denominator is fixed to a forced value of $2^{24} = 16777216$. The waveform always starts at RAMP0 when the LSB of the PLL_N (R16) is written to. After it is set up, it starts at the initial frequency and have piecewise linear frequency modulation that deviates from this initial frequency as specified by the modulation. Each of the eight ramps can be individually programmed. Various settings are as follows:

Table 6. Register Descriptions of the Ramping Function

RAMP CHARACTERISTIC	PROGRAMMING FIELD NAME	DESCRIPTION
Ramp Length	RAMPx_LEN RAMPx_DLY	The user programs the length of the ramp in phase detector cycles. If RAMPx_DLY = 1, then each count of RAMPx_LEN is actually two phase detector cycles.
Ramp Slope	RAMPx_LEN RAMPx_DLY RAMPx_INC	The user does not directly program slope of the line, but rather this is done by defining how long the ramp is and how much the fractional numerator is increased per phase detector cycle. The value for RAMPx_INC is calculated by taking the total expected increase in the frequency, expressed in terms of how much the fractional numerator increases, and dividing it by RAMPx_LEN. The value programmed into RAMPx_INC is actually the two's complement of the desired mathematical value.
Trigger for Next Ramp	RAMPx_NEXT_TRIG	The event that triggers the next ramp can be defined to be the ramp finishing or can wait for a trigger as defined by Trigger A, Trigger B, or Trigger C.
Next Ramp	RAMPx_NEXT	This sets the ramp that follows. Waveforms are constructed by defining a chain ramp segments. To make the waveform repeat, make RAMPx_NEXT point to the first ramp in the pattern.
Ramp Fastlock	RAMPx_FL	This allows the ramp to use a different charge pump current or use Fastlock
Ramp Flags	RAMPx_FLAG	This allows the ramp to set a flag that can be routed to external terminals to trigger other devices.

7.3.11.1 Ramp Count

If it is desired that the ramping waveform keep repeating, then all that is needed is to make the RAMPx_NEXT of the final ramp equal to the first ramp. This runs until the RAMP_EN bit is set to zero. If this is not desired, then one can use the RAMP COUNT to specify how may times the specified pattern is to repeat.

7.3.11.2 Ramp Comparators and Ramp Limits

The ramp comparators and ramp limits use programable thresholds to allow the device to detect whenever the modulated waveform frequency crosses a limit as set by the user. The difference between these is that comparators set a flag to alert the user while a ramp limits prevent the frequency from going beyond the prescribed threshold. In either case, these thresholds are expressed by programming the Extended_Fractional_Numerator. CMP0 and CMP1 are two separated comparators but they work in the same fashion.

Product Folder Links: LMX2491

Extended Fractional Numerator = Fractional Numerator + (N - N*) x 2²⁴

(1)



In Equation 1, N* is the PLL feedback value without ramping. Fractional_Numerator and N are the new values as defined by the threshold frequency. The actual value programmed is the 2's complement of Extended_Fractional_Numerator.

TYPE	PROGRAMMING BIT	THRESHOLD
Domn Limita	RAMP_LIMIT_LOW	Lower Limit
Ramp Limits	RAMP_LIMIT_HIGH	Upper Limit
Ramp Comparators	RAMP_CMP0 RAMP_CMP1	For the ramp comparators, if the ramp is increasing and exceeds the value as specified by RAMP_CMPx, then the flag goes high, otherwise it is low. If the ramp is decreasing and goes below the value as specified by RAMP_CMPx, then the flag goes high, otherwise it is low.

7.3.12 Power-on-reset (POR)

The power-on-reset circuitry sets all the registers to a default state when the device is powered up. This same reset can be done by programming SWRST = 1. In the programming section, the power on reset state is given for all the programmable fields.

7.3.13 Register Readback

The LMX2491 allows any of its registers to be read back. MOD, MUXout, TRIG1 or TRIG2 pin can be programmed to support register-readback serial-data output. To read back a certain register value, follow the following steps:

- 1. Set the R/W bit to 1; the data field contents are ignored.
- 2. Send the register to the device; readback serial data will be output starting at the 17th clock cycle.

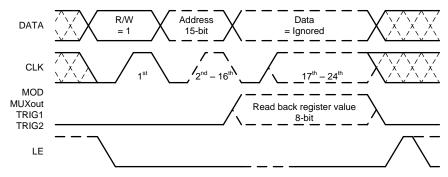


Figure 13. Register Readback Timing Diagram

7.4 Device Functional Modes

The two primary ways to use the LMX2491 are to run it to generate a set of frequencies

7.4.1 Continuous Frequency Generator

In this mode, the LMX2491 generates a single frequency that only changes when the N divider is programmed to a new value. In this mode, the RAMP_EN bit is set to 0 and the ramping controls are not used. The fractional denominator can be programmed to any value from 1 to 16777216. In this kind of application, the PLL is tuned to different channels, but at each channel, the goal is to generate a stable fixed frequency.

7.4.1.1 Integer Mode Operation

In integer mode operation, the VCO frequency needs to be an integer multiple of the phase detector frequency. This can be the case when the output frequency or frequencies are nicely related to the input frequency. As a rule of thumb, if this an be done with a phase detector of as high as the lesser of 10 MHz or the OSCin frequency, then this makes sense. To operate the device in integer mode, disable the fractional circuitry by programming the fractional order (FRAC_ORDER), dithering (FRAC_DITH), and numerator (FRAC_NUM) to zero.



Device Functional Modes (continued)

7.4.1.2 Fractional Mode Operation

In fractional mode, the output frequency does not need to be an integer multiple of the phase detector frequency. This makes sense when the channel spacing is more narrow or the input and output frequencies are not nicely related. There are several programmable controls for this such as the modulator order, fractional dithering, fractional numerator, and fractional denominator. There are many trade-offs with choosing these, but here are some guidelines

Table 8. Fractional Mode Register Descriptions and Recommendations

PARAMETER	FIELD NAME	HOW TO CHOOSE
Fractional Numerator and Denominator	FRAC_NUM FRAC_DEN	The first step is to find the fractional denominator. To do this, find the frequency that divides the phase detector frequency by the channel spacing. For instance, if the output ranges from 5000 to 5050 in 5-MHz steps and the phase detector is 100 MHz, then the fractional denominator is 100 MHz / $5 = 20$. So for a an output of 5015 MHz, the N divider would be $50 + 3/20$. In this case, the fractional numerator is 3 and the fractional denominator is 20. Sometimes when dithering is used, it makes sense to express this as a larger equivalent fraction. Note that if ramping is active, the fractional denominator is forced to 2^{24} .
Fractional Order	FRAC_ORDER	There are many trade-offs, but in general try either the 2nd or 3rd-order modulator as starting points. The 3rd-order modulator may give lower main spurs, but may generate others. Also if dithering is involved, it can generate phase noise.
Dithering	FRAC_DITH	Dithering can reduce some fractional spurs, but add noise. Consult application note AN-1879 Fractional N Frequency Synthesis for more details on this.

7.4.2 Modulated Waveform Generator

In this mode, the device can generate a broad class of frequency sweeping waveforms. The user can specify up to 8 linear segments to generate these waveforms. When the ramping function is running, the denominator is fixed to a forced value of $2^{24} = 16777216$

In addition to the ramping functions, there is also the capability to use a terminal to add phase or frequency modulation that can be done by itself or added on top of the waveforms created by the ramp generation functions.

7.5 Programming

7.5.1 Loading Registers

The device is programmed using several 24-bit registers. Each register consists of a data field, an address field, and a R/W bit. The MSB is the R/W bit. 0 means register write while 1 means register read. The following 15 bits of the register are the address, followed by the next 8 bits of data. The user has the option to pull the LE terminal high after this data, or keep sending data and it applies this data to the next lower register. So instead of sending three registers of 24 bits each, one could send a single 40-bit register with the 16 bits of address and 24 bits of data. For that matter, the entire device could be programmed as a single register if desired.

7.6 Register Maps

Registers are programmed in REVERSE order from highest to lowest. Registers NOT shown in this table or marked as reserved can be written as all 0s unless otherwise stated. The POR value is the power on reset value that is assigned when the device is powered up or the SWRST bit is asserted.

Table 9. Register Map

REGI	STER	D7	D7 D6 D5 D4 D3 D2 D1 D0				POR			
0	0	0	0	0	1	1	0	0	0	0x18
1	0x1		Reserved							
2	0x2	0	0 0 0 0 SWRST POWERDOWN[1:0]					0x00		
3 - 15	0x3 - 0xF		Reserved							-
16	0x10		PLL_N[7:0]							0x64



Register Maps (continued)

Table 9. Register Map (continued)

					jiotoi map	(,			
REGI	STER	D7	D6	D5	D4	D3	D2	D1	D0	POR
17	0x11				PLL_N	N[15:8]				0x00
18	0x12	0	FRA	AC_ORDER[2:0]	FRAC_DI	THER[1:0]	PLL_N	N[17:16]	0x00
19	0x13				FRAC_N	NUM[7:0]				0x00
20	0x14		FRAC_NUM[15:8]							0x00
21	0x15				FRAC_N					0x00
22	0x16				FRAC_[0x00
23	0x17				FRAC_D					0x00
24	0x18				FRAC_DI	EN[23:16]				0x00
25	0x19				PLL_	R[7:0]				0x04
26	0x1A				PLL_F	R[15:8]	T			0x00
27	0x1B	0	FL_CS		PFD_D	LY[1:0]	PLL_R_ DIFF	0	OSC_2X	0x08
28	0x1C	0	0	CPPOL			CPG[4:0]			0x00
29	0x1D	F	FL_TOC[10:8]			FL_CPG[4:0]		0x00
30	0x1E	0	CPM_ FLAGL			CPM_THR	R_LOW[5:0]			0x0A
31	0x1F	0	CPM_ FLAGH			CPM_THR	_HIGH[5:0]			0x32
32	0x20		•		FL_TC	C[7:0]				0x00
33	0x21				DLD_PASS	S_CNT[7:0]				0x0F
34	0x22	[DLD_TOL[2:0]		DLD	_ERR_CNT	R[4:0]		0x00
35	0x23	MOD_ MUX[5]	1	MUXout _MUX[5]	TRIG2 _MUX[5]	TRIG1 _MUX[5]	0	0	1	0x41
36	0x24		TF	RIG1_MUX[4	:0]		Т	RIG1_PIN[2:	:0]	0x08
37	0x25		TF	RIG2_MUX[4	:0]		Т	RIG2_PIN[2:	:0]	0x10
38	0x26		N	IOD_MUX[4:	0]			MOD_PIN[2:0	0]	0x18
39	0x27		MU	JXout_MUX[4	4:0]		M	UXout_PIN[2	2:0]	0x38
40 - 57	0x28 - 0x39				Rese	erved				-
58	0x3A		RAMP_TF	RIG_A[3:0]		0	RAMP_ PM_EN	RAMP_ CLK	RAMP_EN	0x00
59	0x3B		RAMP_TF	RIG_C[3:0]			RAMP_TI	RIG_B[3:0]		0x00
60	0x3C				RAMP_C	MP0[7:0]				0x00
61	0x3D				RAMP_C	MP0[15:8]				0x00
62	0x3E				RAMP_CN	/IP0[23:16]				0x00
63	0x3F				RAMP_CN	/IP0[31:24]				0x00
64	0x40				RAMP_CM	P0_EN[7:0]				0x00
65	0x41				RAMP_C	MP1[7:0]				0x00
66	0x42				RAMP_C	MP1[15:8]				0x00
67	0x43				RAMP_CN	//P1[23:16]				0x00
68	0x44	RAMP_CMP1[31:24]							0x00	
69	0x45	RAMP_CMP1_EN[7:0]						0x00		
70	0x46	0	0 FSK_TRIG[1:0] RAMP_ RAMP_ FSK_ RAMP_ RAMP_ LIML[32] LIML[32] DEV[32] CMP1[32] CMP0[32]						0x08	
71	0x47				FSK_D	EV[7:0]				0x00
72	0x48				FSK_DI	EV[15:8]				0x00
73	0x49				FSK_DE	V[23:16]				0x00
74	0x4A		·	·	FSK DE	V[31:24]		·		0x00



Register Maps (continued)

Table 9. Register Map (continued)

			ı a	Die 3. Ive	gister map (contin	ueu)				
REG	ISTER	D7	D6	D5	D4 D3	D2	D1 D0	POR		
75	0x4B				RAMP_LIMIT_LOW[7:	0]		0x00		
76	0x4C				RAMP_LIMIT_LOW[15	:8]		0x00		
77	0x4D				RAMP_LIMIT_LOW[23:	16]		0x00		
78	0x4E				RAMP_LIMIT_LOW[31:	24]		0x00		
79	0x4F		RAMP_LIMIT_HIGH[7:0]							
80	0x50				RAMP_LIMIT_HIGH[15	:8]		0xFF		
81	0x51				RAMP_LIMIT_HIGH[23:	16]		0xFF		
82	0x52				RAMP_LIMIT_HIGH[31:	24]		0xFF		
83	0x53				RAMP_COUNT[7:0]			0x00		
84	0x54	RAMP_TRI	IG_INC[1:0]	RAMP_ AUTO	R	AMP_COUNT[12:8]	0x00		
85	0x55				Reserved			0x00		
86	0x56				RAMP0_INC[7:0]			0x00		
87	0x57				RAMP0_INC[15:8]			0x00		
88	0x58				RAMP0_INC[23:16]			0x00		
89	0x59	RAMP0_ DLY	RAMP0_ FL)_INC[29:24]		0x00		
90	0x5A	DE.			RAMP0 LEN[7:0]			0x00		
91	0x5B				RAMP0_LEN[15:8]			0x00		
		5.4	MDO NEVER	2.01	RAMP0	RAMP0_	DAMPO EL ACIA OL			
92	0x5C 0x5D	RA	MP0_NEXT[2	2:0]	NEXT_TRIG[1:0] RAMP1_INC[7:0]	RST	RAMP0_FLAG[1:0]	0x00 0x00		
94	0x5E				RAMP1_INC[15:8]			0x00		
95	0x5F	DAMD4	DAMDA		RAMP1_INC[23:16]			0x00		
96	0x60	RAMP1_ DLY	RAMP1_ FL			_INC[29:24]		0x00		
97	0x61				RAMP1_LEN[7:0]			0x00		
98	0x62				RAMP1_LEN[15:8]		Г	0x00		
99	0x63	RA	MP1_NEXT[2	2:0]	RAMP1_ NEXT_TRIG[1:0]	RAMP1_ RST	RAMP1_FLAG[1:0]	0x00		
100	0x64				RAMP2_INC[7:0]			0x00		
101	0x65				RAMP2_INC[15:8]			0x00		
102	0x66				RAMP2_INC[23:16]			0x00		
103	0x67	RAMP2 DLY	RAMP2_ FL		RAMP2	2_INC[29:24]		0x00		
104	0x68				RAMP2_LEN[7:0]			0x00		
105	0x69				RAMP2_LEN[15:8]			0x00		
106	0x6A	RA	MP2_NEXT[2	2:0]	RAMP2_ NEXT_TRIG[1:0]	RAMP2_ RST	RAMP2_FLAG[1:0]	0x00		
107	0x6B		RAMP3_INC[7:0]							
108	0x6C	RAMP3_INC[15:8]								
109	0x6D	RAMP3_INC[23:16]								
110	0x6E	RAMP3_ DLY	RAMP3_ FL		RAMP3	3_INC[29:24]		0x00		
111	0x6F		1	 	RAMP3_LEN[7:0]			0x00		
112	0x70				RAMP3_LEN[15:8]			0x00		
113	0x71	RA	MP3_NEXT[2	2:0]	RAMP3_ NEXT_TRIG[1:0]	RAMP3_ RST	RAMP3_FLAG[1:0]	0x00		



Register Maps (continued)

Table 9. Register Map (continued)

REG	ISTER	D7	D6	D5	D4	D3	D2	D1	D0	POR
114	0x72				RAMP4	_INC[7:0]				0x00
115	0x73				RAMP4_	INC[15:8]				0x00
116	0x74				RAMP4_	NC[23:16]				0x00
117	0x75	RAMP4_ DLY	RAMP4_ FL	RAMP4_INC[29:24]						0x00
118	0x76				RAMP4_	LEN[7:0]				0x00
119	0x77				RAMP4_	LEN[15:8]				0x00
120	0x78	RAMP4_NEXT[2:0] RAMP4_ RAMP4_ RAMP4_FLAG[1:0]					0x00			
121	0x79				RAMP5	_INC[7:0]				0x00
122	0x7A				RAMP5_	INC[15:8]				0x00
123	0x7B				RAMP5_	NC[23:16]				0x00
124	0x7C	RAMP5_ DLY	RAMP5_ FL			RAMP5_	INC[29:24]			0x00
125	0x7D				RAMP5_	LEN[7:0]				0x00
126	0x7E				RAMP5_	LEN[15:8]				0x00
127	0x7F	RAMP5_NEXT[2:0]					0x00			
128	0x80				RAMP6	_INC[7:0]				0x00
129	0x81				RAMP6_	INC[15:8]				0x00
130	0x82				RAMP6_	NC[23:16]				0x00
131	0x83	RAMP6_ DLY	RAMP6_ FL			RAMP6_	INC[29:24]			0x00
132	0x84				RAMP6_	LEN[7:0]				0x00
133	0x85				RAMP6_	LEN[15:8]				0x00
134	0x86	RA	MP6_NEXT[2:0]		/IP6_ TRIG[1:0]	RAMP6_ RST	RAMP6_	FLAG[1:0]	0x00
135	0x87				RAMP7	_INC[7:0]	•			0x00
136	0x88				RAMP7_	INC[15:8]				0x00
137	0x89				RAMP7_	NC[23:16]				0x00
138	0x8A	RAMP7_ DLY	RAMP7_ FL			RAMP7_	INC[29:24]			0x00
139	0x8B	RAMP7_LEN[7:0]						0x00		
140	0x8C		RAMP7_LEN[15:8]						0x00	
141	0x8D	RA	MP7_NEXT[2:0]	RAN		RAMP7_ RST	RAMP7_	FLAG[1:0]	0x00
142 - 32767	0x8E - 0x7FFF				Res	erved				0x00



7.6.1 Register Field Descriptions

The following sections go through all the programmable fields and their states. Additional information is also available in the applications and feature descriptions sections as well. The POR column is the power on reset state that this field assumes if not programmed.

7.6.1.1 POWERDOWN and Reset Fields

Table 10. POWERDOWN and Reset Fields

FIELD	LOCATION	POR	DESCRIPTION AND STATES		
			POWERDOWN Control	Value	POWERDOWN State
				0	Power Down, ignore CE
POWERDOWN	R2[1:0]	0		1	Power Up, ignore CE
[1:0]		o di		2	Power State Defined by CE terminal state
				3	Reserved
	R2[2]	0		Value	Reset State
SWRST			Software Reset. Setting this bit sets all registers to their POR default values.	0	Normal Operation
			registers to their r ere delaute values.	1	Register Reset

Product Folder Links: LMX2491

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7.6.1.2 Dividers and Fractional Controls

Table 11. Dividers and Fractional Controls

FIELD	LOCATION	POR	DESCRIPTION AND STATES		S				
PLL_N [17:0]	R18[1] to R16[0]	16		Feedback N counter Divide value. Minimum count is 16. Maximum is 262132 the register R16 begins any ramp execution when RAMP_EN = 1.					
				Value	Dither				
				0	Weak				
FRAC_ DITHER [1:0]	R18[3:2]	0	Dither used by the fractional modulator	1	Medium				
[1.0]				2	Strong				
				3	Disabled				
				Value	Modulator Order				
				0	Integer Mode				
				1	1st Order Modulator				
FRAC_ ORDER [2:0]	R18[6:4]	0	Fractional Modulator order	2	2nd Order Modulator				
[2.0]				3	3rd Order Modulator				
				4	4th Order Modulator				
				5-7	Reserved				
FRAC_NUM [23:0]	R21[7] to R19[0]	0	Fractional Numerator. This value should denominator.	be less tha	n or equal to the fractional				
FRAC_DEN [23:0]	R24[7] to R22[0]	0	Fractional Denominator. If RAMP_EN = 1, fixed to 2^{24} .	this field is ig	gnored and the denominator is				
PLL_R [15:0]	R26[7] to R25[0]	1	Reference Divider value. Selecting 1 bypass	Reference Divider value. Selecting 1 bypasses counter.					
	R27[0]	0	Fachlas the Backlas before the Before	Value	Doubler				
OSC_2X			Enables the Doubler before the Reference divider	0	Disabled				
				1	Enabled				
	R27[2]		Enables the Differential R counter.	Value	R Divider				
PLL_R _DIFF		0	This allows for higher OSCin frequencies, but restricts PLL_R to divides of 2, 4, 8 or	0	Single-Ended				
			16.	1	Differential				
	R27[4:3]							Value	Pulse Width
			Sets the charge pump minimum pulse	0	Reserved				
PFD_DLY [1:0]		1	width. This could potentially be a trade-off between fractional spurs and phase noise. Setting 1 is recommended for general use.	1	860 ps				
[1.0]				2	1200 ps				
				3	1500 ps				
				Value	Charge Pump State				
				0	Tri-State				
CPG	D00[4 0]	•	Ol annu muun main	1	100 μΑ				
[4:0]	R28[4:0]	0	Charge pump gain	2	200 μΑ				
				31	3100 μΑ				
			Charge pump polarity is used to	Value	Charge Pump Polarity				
			accommodate VCO with either polarity so that feedback of the PLL is always correct.	0	Positive				
CPPOL	R28[5]	R28[5] 0	IF reference (R) output is faster than feedback (N) output, R28[5]==0 THEN charge pump will source current R28[5]==1 THEN charge pump will sink current	1	Negative				



7.6.1.2.1 Speed Up Controls (Cycle Slip Reduction and Fastlock)

Table 12. FastLock and Cycle Slip Reduction

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FIELD	LOCATION	POR	DESCRIPTION	AND STATE	≣S	
			Cycle Slip Reduction (CSR) reduces the	Value	CSR Value	
			phase detector frequency by multiplying both the R and N counters by the CSR	0	Disabled	
			value while either the FastLock Timer is	1	x 2	
FL_ CSR	R27[6:5]	0	counting or the RAMPx_FL = 1 and the part is ramping. Care must be taken that	2	x 4	
[1:0]			the R and N divides remain inside the range of the counters. Cycle slip reduction is generally not recommended during ramping.	3	Reserved	
	R29[4:0]			Value	Fastlock Charge Pump Gain	
			Charge pump gain only when Fast Lock Timer is counting down or a ramp is running with RAMPx_FL = 1	0	Tri-State	
FL_ CPG		0		1	100 μΑ	
[4:0]				2	200 μΑ	
				•••		
				31	3100 μΑ	
			Fast Lock Timer. This counter starts	Value	Fastlock Timer Value	
			counting when the user writes the PLL_N(Register R16). During this time the	0	Disabled	
FL_ TOC	R29[7:5]		FL_CPG gain is sent to the charge pump,	1	1 x 32 = 32	
[10:0]	and R32[7:0]	0	and the FL_CSR shifts the R and N counters if enabled. When the counter			
			terminates, the normal CPG is presented and the CSR undo's the shifts to give a normal PFD frequency.	2047	2047 x 32 = 65504	



7.6.2 Lock Detect and Charge Pump Monitoring

Table 13. Lock Detect and Charge Pump Monitor

FIELD	LOCATION	POR	DESCRIPTION AND STATES		
				Value	Threshold
CPM_THR _LOW	D00[F.0]	004	Charge pump voltage low threshold value.	0	Lowest
[5:0]	R30[5:0]	0x0A	When the charge pump voltage is below this threshold, the LD goes low.		
			, ,	63	Highest
				Value	Flag Indication
CPM_FLAGL	R30[6]	-	This is a read only bit. Low indicates the charge pump voltage is	0	Charge pump is below CPM_THR_LOW threshold
			below the minimum threshold.	1	Charge pump is above CPM_THR_LOW threshold
				Value	Threshold
CPM_THR _HIGH	D24[5.0]	000	Charge pump voltage high threshold value.	0	Lowest
[5:0]	R31[5:0]	0x32	When the charge pump voltage is above this threshold, the LD goes low.		
			, ,	63	Highest
	R31[6]		This is a read only bit. Charge pump voltage high comparator reading. High indicates the charge pump voltage is above the maximum threshold.	Value	Threshold
CPM_FLAGH		-		0	Charge pump is below CPM_THR_HIGH threshold
				1	Charge pump is above CPM_THR_HIGH threshold
DLD_ PASS_CNT [7:0]	R33[7:0]	0xFF	Digital Lock Detect Filter amount. There mu and less than DLD_ERR edges before the D smaller speeds the detection of lock, but also	LD is conside	ered in lock. Making this number
DLD_ ERR_CNT [4:0]	R34[4:0]	0	Digital Lock Detect error count. This is th DLD_TOL that are allowed before DLD is recommended value is 4.		
				Value	Window and f _{PD} Frequency
				0	1 ns (f _{PD} > 130 MHz)
			Digital Lock detect edge window. If both N and R edges are within this window, it is considered a "good" edge. Edges that are	1	1.7 ns (80 MHz < f _{PD} ≤ 130 MHz)
DLD _TOL	D24[7:5]	0	farther apart in time are considered "error"	2	3 ns (60 MHz < f _{PD} ≤ 80 MHz)
[2:0]	R34[7:5]	U	edges. Window choice depends on phase	3	6 ns (45 MHz < f _{PD} ≤ 60 MHz)
			detector frequency, charge pump minimum pulse width, fractional modulator order and the users desired margin.	4	10 ns (30 MHz < f _{PD} ≤ 45 MHz)
				5	18 ns (f _{PD} ≤ 30 MHz)
				6 and 7	Reserved



7.6.3 TRIG1, TRIG2, MOD, and MUXout Pins

Table 14. TRIG1, TRIG2, MOD, and MUXout Terminal States

FIELD	LOCATION	POR	DESCRIPTION	AND STATE	ES .
				Value	Pin Drive State
TRIG1 _PIN	D26[2.0]	0		0	TRISTATE (default)
[2:0]	R36[2:0]	U		1	Open Drain Output
				2	Pullup / Pulldown Output
TRIG2 _PIN [2:0]	R37[2:0]	0	This is the terminal drive state for the	3	Reserved
MOD_ PIN [2:0]	R38[2:0]	0	TRIG1, TRIG2, MOD, and MUXout Pins	4	GND
				5	Inverted Open Drain Output
MUXout_ PIN [2:0]	R39[2:0]	0		6	Inverted Pullup / Pulldown Output
				7	Input



Table 15. TRIG1, TRIG2, MOD, and MUXout Selections

FIELD	LOCATION	POR	DESCRIPTION	AND STATI	ES
				Value	MUX State
				0	GND
				1	Input TRIG1
				2	Input TRIG2
				3	Input MOD
				4	Output TRIG1 after synchronizer
				5	Output TRIG2 after synchronizer
				6	Output MOD after synchronizer
				7	Output Read back
				8	Output CMP0
				9	Output CMP1
				10	Output LD (DLD good AND CPM good)
				11	Output DLD
				12	Output CPMON good
				13	Output CPMON too High
				14	Output CPMON too low
TRIG1_MUX [5:0]	R36[7:3], R35[3]	1	These fields control what signal is muxed to or from the TRIG1, TRIG2, MOD, and MUXout pins.	15	Output RAMP LIMIT EXCEEDED
TRIG2_MUX	R37[7:3],	2	Some of the abbreviations used are:	16	Output R Divide/2
[5:0]	R35[4]	_	COMP0, COMP1: Comparators 0 and 1 LD, DLD: Lock Detect, Digital Lock Detect	17	Output R Divide/4
MOD_MUX	R38[7:3],	3		18	Output N Divide/2
[5:0]	R35[7]		CPG: Charge Pump Gain	19	Output N Divide/4
MUXout_MUX [5:0]	R39[7:3], R35[5]	7	CPUP: Charge Pump Up Pulse	20	Reserved
[0.0]	1,00[0]		CPDN: Charge Pump Down Pulse	21	Reserved
				22	Output CMP0RAMP
				23	Output CMP1RAMP
				24	Reserved
				25	Reserved
				26	Reserved
				27	Reserved
				28	Output Faslock
				29	Output CPG from RAMP
				30	Output Flag0 from RAMP
				31	Output Flag1 from RAMP
				32	Output TRIGA
				33	Output TRIGB
				34	Output TRIGC
				35	Output R Divide
				36	Output CPUP
				37	Output CPDN
				38	Output RAMP_CNT Finished
				39 to 63	Reserved



7.6.4 Ramping Functions

Table 16. Ramping Functions

FIELD	LOCATION	POR	DESCRIPTION	I AND STATE	:S	
			Enables the RAMP functions. When this bit	Value	Ramp	
D.111D 511	Dector		is set, the Fractional Denominator is fixed	0	Disabled	
RAMP_EN	R58[0]	0	to 2 ²⁴ . RAMP execution begins at RAMP0 upon the PLL_N[7:0] write. The Ramp should be set up before RAMP_EN is set.	1	Enabled	
			RAMP clock input source. The ramp can	Value	Source	
RAMP_CLK	R58[1]	0	be clocked by either the phase detector clock or the MOD terminal based on this	0	Phase Detector	
			selection.	1	MOD Terminal	
				Value	Modulation Type	
RAMP_PM_EN	R58[2]	0	Phase modulation enable.	0	Frequency Modulation	
				1	Phase Modulation	
				Value	Source	
				0	Never Triggers (default)	
				1	TRIG1 terminal rising edge	
				2	TRIG2 terminal rising edge	
				3	MOD terminal rising edge	
				4	DLD Rising Edge	
RAMP_TRIGA	D50[7.4]			5	CMP0 detected (level)	
[3:0]	R58[7:4]			6	RAMPx_CPG Rising edge	
RAMP_TRIGB	R59[3:0]	0	Trigger A, B, and C Sources	7	RAMPx_FLAG0 Rising edge	
[3:0]				8	Always Triggered (level)	
RAMP_TRIGC [3:0]	R59[7:4]			9	TRIG1 terminal falling edge	
[5.0]				10	TRIG2 terminal falling edge	
				11	MOD terminal falling edge	
				12	DLD Falling Edge	
				13	CMP1 detected (level)	
				14	RAMPx_CPG Falling edge	
				15	RAMPx_FLAG0 Falling edge	
RAMP_CMP0 [32:0]	R70[0], R63[7] to R60[0]	0	Twos compliment of Ramp Comparator 0 va R70.			
RAMP_CMP0_EN [7:0]	R64[7:0]	0	Comparator 0 is active during each RAMP or is active in and 0 for ramps it should be ignor corresponds to R64[7]			
RAMP_CMP1 [32:0]	R70[1], R68[7] to R65[0]	0	Twos compliment of Ramp Comparator 1 va R70.	llue. Be awar	e of that the MSB is in Register	
RAMP_CMP1_EN [7:0]	R69[7:0]	0	Comparator 1 is active during each RAMP or is active in and 0 for ramps it should be ignor corresponds to R64[7].			
				Value	Trigger	
			Deviation trigger source. When this trigger	0	Always Triggered	
FSK_TRIG [1:0]	R76[4] to R75[3]	0		1	Trigger A	
[1.0]				2	Trigger B	
				3	Trigger C	
FSK_DEV [32:0]	R70[2], R74[7] to R71[0]	0	Twos compliment of the deviation value for frequency modulation and phase modulation This value should be written with 0 when not used. Be aware that the MSB is in Registe R70.			



Table 16. Ramping Functions (continued)

FIELD	LOCATION	POR	DESCRIPTION AND STATES				
RAMP_LIMIT_LOW [32:0]	R70[3], R78[7] to R75[0]	0	Twos compliment of the ramp lower limit that the ramp can not go below . The ramp limit occurs before any deviation values are included. Care must be taken if the deviation is used and the ramp limit must be set appropriately. Be aware that the MSB is in Register R70.				
RAMP_LIMIT_HIGH [32:0]	R70[4], R82[7] to R79[0]	0x1FF FFFF FF	Twos compliment of the ramp higher limit that the ramp can not go above. The ramp limit occurs before any deviation values are included. Care must be taken if the deviation is used and the ramp limit must be set appropriately. Be aware that the MSB is in Register R70.				
RAMP_COUNT [12:0]	R84[4] to R83[0]	0	Number of RAMPs that is executed before a trigger or ramp enable is brought down. Load zero if this feature is not used. Counter is automatically reset when RAMP_EN goes from 0 to 1.				
	R84[5]	0	Automatically clear RAMP_EN when RAMP Count hits terminal count.	Value	Ramp		
RAMP AUTO				0	RAMP_EN unaffected by ramp counter (default)		
107.010	110 1[0]			1	RAMP_EN automatically brought low when ramp counter terminal counts		
				Value	Source		
RAMP_TRIG_INC			Increment Trigger source for RAMP	0	Increments occur on each ramp transition		
[1:0]	R84[7:6]	0	Counter. To disable ramp counter, load a count value of 0.	1	Increment occurs on Trigger A		
			Count value of 0.	2	Increment occurs on Trigger B		
				3	Increment occurs on Trigger C		



7.6.5 Individual Ramp Controls

These bits apply for all eight ramp segments. For the field names, x can be 0, 1, 2, 3, 4, 5, 6, or 7.

Table 17. Individual Ramp Controls

FIELD	LOCATI ON	POR	DESCRIPTION AND STATES								
RAMPx _INC[29:0]	Varies	0	Signed ramp increment.								
				Value	CPG						
RAMPx _FL	Varies	0	This enables fastlock and cycle slip reduction for ramp x.	0	Disabled						
				1	Enabled						
				Value	Clocks						
RAMPx _DLY	Varies	0	During this ramp, each increment takes 2 f _{PD} cycles per LEN clock instead of the normal 1 f _{PD} cycle. Slows the ramp by a factor of 2.	0	1 f _{PD} clock per RAMP tick.(default)						
			Tamp by a lactor of E.	1	2 f _{PD} clocks per RAMP tick.						
RAMPx _LEN	Varies	0	Number of f_{PD} clocks (if DLY is 0) to continue to increme Maximum of 65536 cycles.	Number of f_{PD} clocks (if DLY is 0) to continue to increment RAMP. 1 = 1 cycle, 2 = 2 cycles, etc. Maximum of 65536 cycles.							
		Varies 0			Value	Flag					
				0	Both FLAG1 and FLAG0 are zero. (default)						
RAMPx _FLAG[1:0]	Varies		General purpose FLAGs sent out of RAMP at the start of a ramp pattern.	1	FLAG0 is set, FLAG1 is clear						
_1 [70[1.0]	_FLAG[1.0]			2	FLAG0 is clear, FLAG1 is set						
				3	Both FLAG0 and FLAG1 are set.						
			Forces a clear of the ramp accumulator at the start of a	Value	Reset						
RAMPx _RST	Varies	0	ramp pattern. This is used to erase any accumulator creep	0	Disabled						
_1.01			that can occur depending on how the ramps are defined.	1	Enabled						
				Value	Operation						
RAMPx_			Determines what event is necessary to cause the state	0	RAMPx_LEN						
	NEXT _TRIG [1:0] Varies	ries 0	machine to go to the next ramp. It can be set to when the RAMPx LEN counter reaches zero or one of the events for	1	Trigger A						
			Triggers A, B, or C.	2	Trigger B						
			3	Trigger C							
RAMPx _NEXT[2:0]	Varies	0	The next RAMP to execute when the length counter times out								

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8 Applications and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LMX2491 can be used in a broad class of applications such as generating a single frequency for a high frequency clock, generating a tunable range of frequencies, or generating swept waveforms that can be used in applications such as radar.

8.2 Typical Application

Figure 14 is an example that could be used in a typical application.

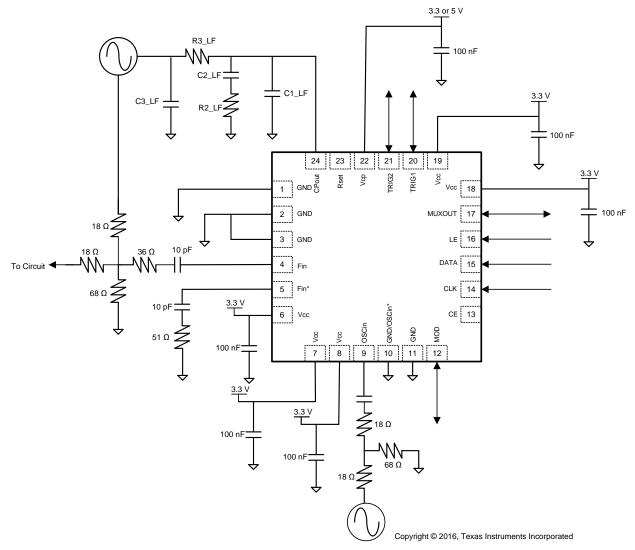


Figure 14. Typical Schematic



Typical Application (continued)

8.2.1 Design Requirements

For these examples, it will be assumed that there is a 100 MHz input signal and the output frequency is between 1500 and 1520 MHz with various modulated waveforms.

Table 18. Design Requirements

PARAMETER	SYMBOL	VALUE	COMMENTS
Input frequency	f _{OSCin}	100 MHz	
Phase detector frequency	f _{PD}	50 MHz	There are many possibilities, but this choice gives good performance.
VCO frequency	f _{vco}	1500 - 1520 MHz	In the different examples, the VCO frequency is actually changing. However, the same loop filter design can be used for all examples. Unmodulated VCO frequency or steady state VCO frequency without ramp is 1500 MHz.
VCO gain	K _{VCO}	65 MHz/V	This parameter has nothing to do with the LMX2491, but is rather set by the external VCO choice.

8.2.2 Detailed Design Procedure

The first step is to calculate the reference divider (PLL_R) and feedback divider (PLL_N) values as shown in the table that follows.

Table 19. Detailed Design Procedure

PARAMETE			
R	SYMBOL AND CALCULATIONS	VALUE	COMMENTS
Average VCO frequency	$f_{VCOavg} = (f_{VCOmax} + f_{VCOmin}) / 2$	1510 MHz	To design a loop filter, one designs for a fixed VCO value, although it is understood that the VCO will tune around. This typical value is usually chosen as the average VCO frequency
VCO gain	K _{VCO}	65 MHz/V	This parameter has nothing to do with LMX2491, but is rather set by the external VCO choice. In this case, it was the CVCO55BE-1400-1624 VCO.
VCO input capacitance	C _{VCO}	120 pF	This parameter has nothing to do with LMX2491, but is rather set by the external VCO choice.
PLL loop bandwidth	LBW	380 kHz	This bandwidth is very wide to allow the VCO frequency to be modulated.
Charge pump gain	CPG	3.1 mA	Using the larger gain allows a wider loop bandwidth and gives good phase performance.
R-divider	$PLL_R = f_{OSCin} / f_{PD}$	2	
N-divider	$PLL_N = f_{VCO} / f_{PD}$	96	
	C1_LF	68 pF	
	C2_LF	3.9 nF	
Loop filter components	C3_LF	150 pF	These were calculated by TI PLLatinum Simulator Tool.
Components	R2_LF	390 Ω	
	R3_LF	150 Ω	

Once a loop filter bandwidth is chosen, the external loop filter component values can be calculated with a tool such as PLLatinum Simulator Tool. It is also highly recommended to look at the EVM User's Guide. TICS Pro software is an excellent starting point and example to see how to program this device.

8.2.3 TICS Pro Basic Setup

In the following application examples, TICS Pro is used to program the device to implement different ramp profiles. The following procedure shows how to setup TICS Pro to put the device to lock to 1500 MHz without modulation or ramp.



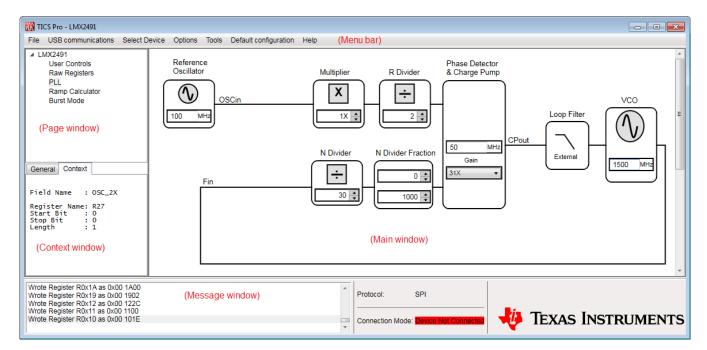


Figure 15. TICS Pro

- 1. In the Menu bar, click Select Device and then select LMX2491.
- 2. In the Menu bar, click Default Configuration and then select Default Mode.
- 3. In the Page window, click PLL.
- 4. In the Main window, change R Divider value to 2 and VCO value to 1500.
- 5. In the Menu bar, click USB Communications and then click Write All Registers. The device is now locked to 1500 MHz.

Other TICS Pro fundamentals:

- When a particular content in the Main window is moused-over, the Context window will show a brief description of that content.
- An alternative method to write all registers is press the Ctrl key and L key from the keyboard.
- Whenever a value is updated in the Main window, the Message window will show which register is being updated

8.2.4 Frequency Shift Keying Example

FSK operation requires an external input trigger signal at either MOD, TRIG1 or TRIG2 pin. In this example, MOD pin is selected as the Trigger A source. A 20 kHz square-wave clock will be applied to MOD pin to toggle the RF output to switch between 1500 MHz and 1502 MHz. That is, FSK frequency deviation is 2 MHz. The following register bits are required to set in order to initiate FSK operation.

Table 20. FSK Register Settings

PARAMETER	REGISTER BIT	SETTING	COMMENTS
Frequency deviation	FSK_DEV	671089 = 2 MHz	Frequency deviation = (f _{PD} x FSK_DEV) / 2 ²⁴
MOD pin characteristic	MOD_PIN	7 = Input	Set MOD pin as an input pin
FSK trigger source	FSK_DEV_TRIG	1 = Trigger A	Use Trigger A to trigger FSK
Trigger source definition	RAMP_TRIGA	3 = MOD Rising Edge	When there is a L-to-H transition at MOD pin, the set amount of frequency deviation will be added to the unmodulated carrier
Enable ramp	RAMP_EN	1 = Enabled	Activate FSK operation



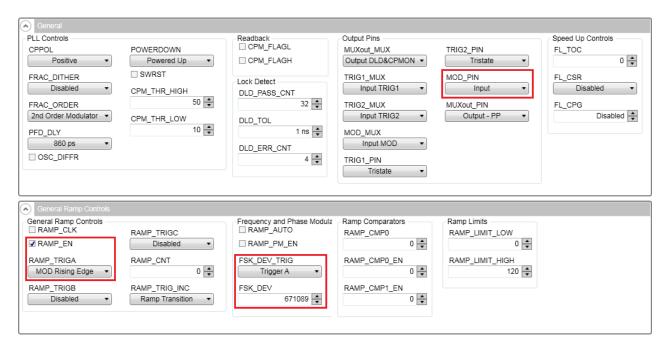


Figure 16. TICS Pro FSK Configuration

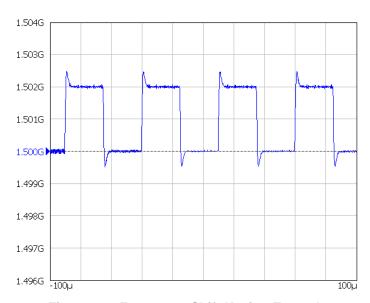


Figure 17. Frequency Shift Keying Example

8.2.5 Single Sawtooth Ramp Example

In this example, Trigger B is used to trigger the ramp generator of LMX2491 to general a single frequency ramp between 1500 MHz and 1520 MHz. Ramp duration is 50 µs. The ramp will finish and return back to 1500 MHz immediately when the output frequency reaches 1520 MHz. Trigger 1 pin is assigned as Trigger B source.

Two ramp segments are setup to create this one-time single ramp. RAMP0 is used to establish a trigger for the second ramp segment - RAMP1. When a trigger signal is received, RAMP1 will execute and bring the output frequency to 1520 MHz in $50 \mu s$.



Table 21. Single Sawtooth Ramp Register Settings

PARAMETER	REGISTER BIT	SETTING	COMMENTS
Set maximum ramp frequency threshold	RAMP_LIMIT_HIGH	16777216 = 1550 MHz	This threshold frequency can be anything above 1520 MHz. The fractional numerator is equal to 0 at 1550 MHz. The N-Divider difference between 1500 MHz and 1550 MHz is 1. From Equation 1, this threshold is equal to $0 + (1 \times 2^{24}) = 16777216$.
Set minimum ramp frequency threshold	RAMP_LIMIT_LOW	8573157376 = 1450 MHz	This threshold frequency can be anything below 1500 MHz. This threshold is equal to –16777216. This is a 33-bit long register, 2's complement is therefore equal to 8573157376.
Number of ramp in each ramp segment	RAMP0_LEN, RAMP1_LEN	2500 = for ramp duration equals 50 μs	The duration of RAMP0 is not matter, for demonstration convenience, it has the same ramp duration as RAMP1. During ramp, LMX2491 ramp generator will increment its output frequency once per phase detector cycle. For ramp duration of 50 μs and f_{PD} = 50 MHz, there are 2500 ramps [= 50 μs / (1 / 50 MHz)].
Frequency change per ramp in RAMP0	RAMP0_INC	0	Since the output frequency would not change in RAMP0, there is no frequency increment.
Set next ramp segment	RAMP0_NEXT	1 = RAMP1	Set RAMP1 as the next ramp segment following RAMP0.
Set next ramp segment trigger source	RAMP0_NEXT_TRIG	2 = Trigger B	Use Trigger B to trigger the execution of RAMP1.
Rest fractional numerator	RAMP0_RST	1 = Reset	RAMP0 will execute again after RAMP1 is finished but RAMP1 does not end at 1500 MHz, a reset to the fractional numerator is required before RAMP0 is executed.
Frequency change per ramp in RAMP1	RAMP1_INC	2684 = 8 kHz	Between 1500 MHz and 1520 MHz, there are 2500 ramps. For each ramp, the output frequency will increment by 20 MHz / 2500 = 8 kHz. For f_{PD} = 50 MHz and fractional denominator = 2^{24} , fractional numerator is incremented by a value of (8 kHz x 2^{24}) / 50 MHz ≈ 2684.
Set next ramp segment	RAMP1_NEXT	0 = RAMP0	Set RAMP0 as the next ramp segment following RAMP1.
Set next ramp segment trigger source	RAMP1_NEXT_TRIG	0 = TOC Timeout	After RAMP1 is finished, the next ramp segment will execute immediately.
Trigger source definition	RAMP_TRIGB	1 = TRIG1 Rising Edge	When there is a L-to-H transition at TRIG1 pin, RAMP1 will execute.
TRIG1 pin characteristic	TRIG1_PIN	7 = Input	Set TRIG1 pin as an input pin.



It is recommended to use the Ramp Calculator in TICS Pro to create the ramp profile. TICS Pro will calculate the ramp-related register values automatically.

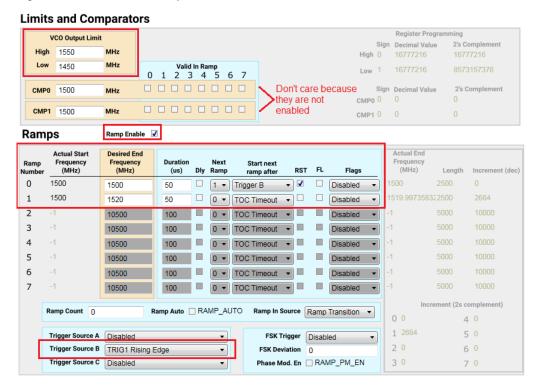


Figure 18. TICS Pro Ramp Calculator

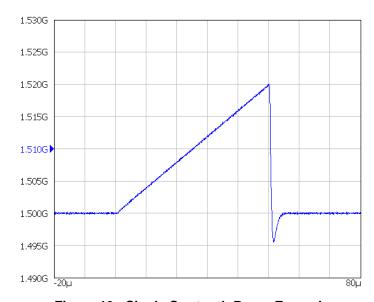


Figure 19. Single Sawtooth Ramp Example

8.2.6 Continuous Sawtooth Ramp Example

This example shows how to generate a continuous sawtooth ramp. Only one ramp segment is necessary as it will loop back to itself.



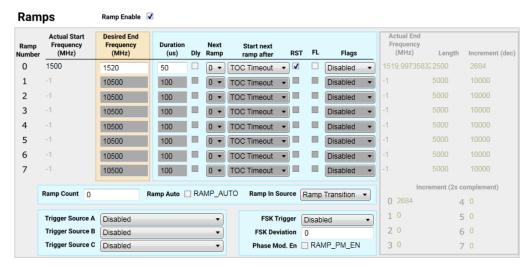


Figure 20. Continuous Sawtooth Ramp Configuration

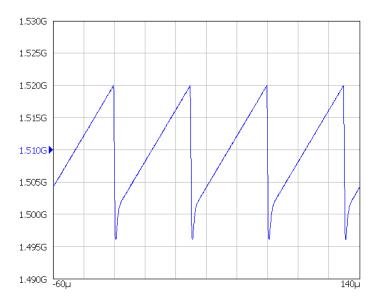


Figure 21. Continuous Sawtooth Ramp Example

8.2.7 Continuous Sawtooth Ramp with FSK Example

A ramp and FSK can coexist at the same time. Since the amount of FSK is added to the instantaneous carrier, the FSK will appear at the envelope of the ramp. Furthermore, a ramp and FSK are two independent operations, their register settings can be combined in a single configuration setting. That is, when RAMP_EN is enabled, both frequency ramp and FSK will be activated together.



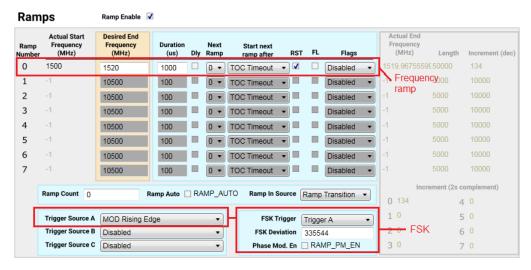


Figure 22. Continuous Sawtooth Ramp with FSK Configuration

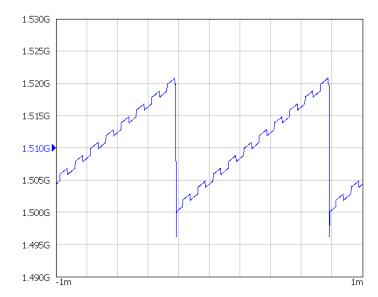


Figure 23. Continuous Sawtooth Ramp with FSK Example

8.2.8 Continuous Triangular Ramp Example

Two ramp segments are used to create this ramp pattern. RAMP0 ramps from 1500 MHz to 1520 MHz. RAMP1 brings the frequency back to 1500 MHz and then RAMP0 starts over again. Since RAMP1 already brought the frequency back to 1500 MHz, which is also the start frequency of RAMP0, a reset to fractional numerator is not required.



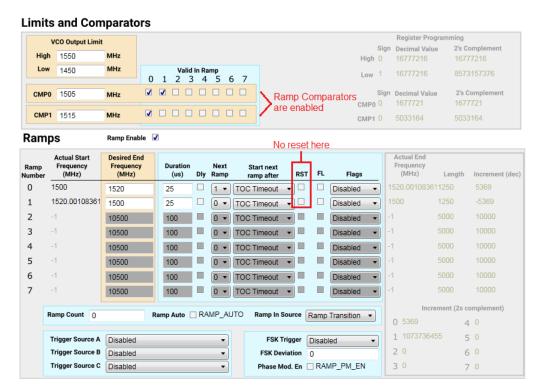


Figure 24. Continuous Triangular Ramp Configuration

Ramp comparators are enabled so as to output flag signals when the threshold frequencies are hit. MOD pin is assigned for CMP0 while TRIG1 pin is assigned for CMP1. RAMP_CMP0_EN is equal to 3 because ramp segment 0 and 1 are monitored.

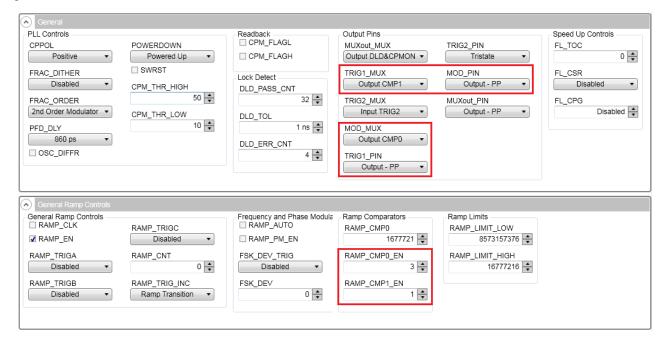


Figure 25. Ramp Comparators Configuration



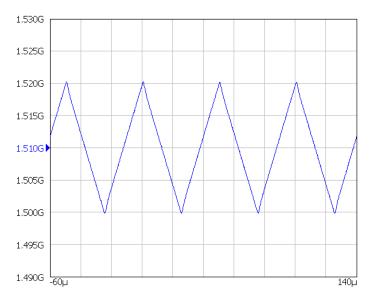


Figure 26. Continuous Triangular Ramp Example

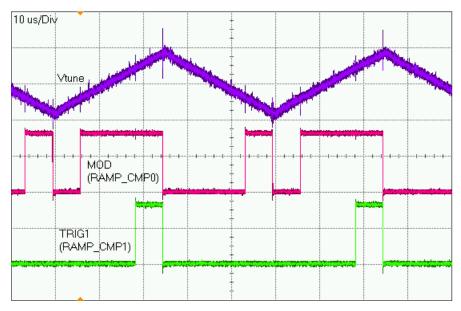


Figure 27. Ramp Comparators Output Flags

8.2.9 Continuous Trapezoid Ramp Example

This is a long-ramp example, the ramp duration is 2 ms. Since f_{PD} = 50 MHz, 100000 ramps are required for each ramp segment. However, LMX2491 supports up to a maximum ramp length (RAMPx_LEN) of 65536 only. There are two solutions to resolve this problem:

- 1. Reduce phase detector frequency. For example, reduce f_{PD} to 25 MHz, then the required RAMPx_LEN becomes 50000.
- 2. Enable RAMPx_DLY. When this register bit is set, the ramp generator will ramp every 2 phase detector cycles instead of the normal 1 f_{PD} cycle. In this example, this bit is set and as a result, RAMPx_LEN is 50000.

Four ramp segments are used to construct the ramp pattern. Again there is no need to reset the fractional numerator because the last ramp end frequency is equal to the first ramp start frequency.



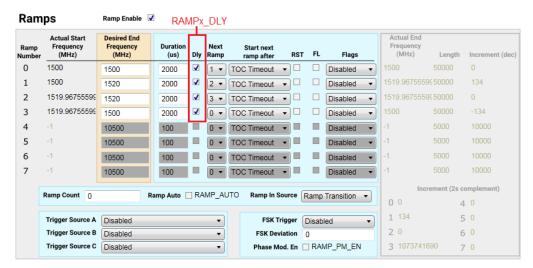


Figure 28. Continuous Trapezoid Ramp Configuration

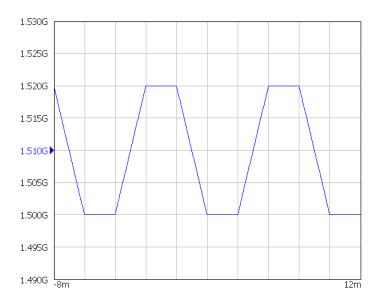


Figure 29. Continuous Trapezoid Ramp Example

8.2.10 Arbitrary Waveform Ramp Example

An arbitrary ramp waveform can be easily constructed with the 8 ramp segments provided in LMX2491. LMX2491 also provides flag signals output to indicate the start of a ramp. This example used the MOD pin to initiate the ramp and used TRIG1 and TRIG2 as the output flags to indicate the status of the ramp.

Product Folder Links: LMX2491



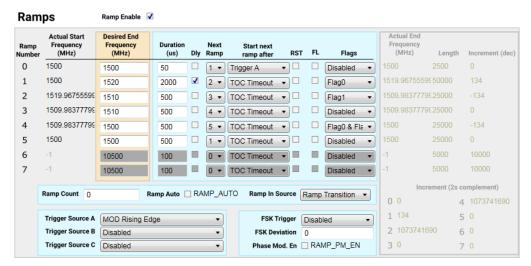


Figure 30. Arbitrary Waveform Ramp Configuration

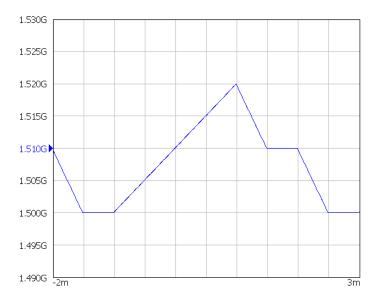


Figure 31. Arbitrary Waveform Ramp Example

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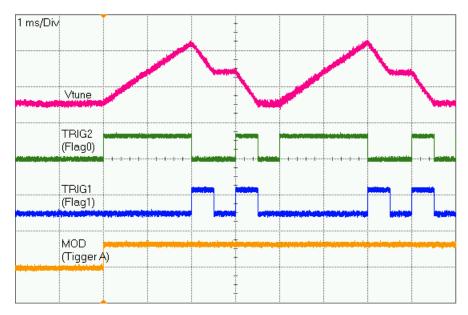


Figure 32. Arbitrary Waveform Ramp Timing

9 Power Supply Recommendations

For power supplies, TI recommends placing 100 nF close to each of the power supply pins. If fractional spurs are a large concern, using a ferrite bead to each of these power supply pins can reduce spurs to a small degree.

10 Layout

10.1 Layout Guidelines

For layout examples, the EVM instructions are the most comprehensive document. In general, the layout guidelines are similar to most other PLL devices. For the high frequency Fin pin, it is recommended to use 0402 components and match the trace width to these pad sizes. Also the same needs to be done on the Fin* pin. If layout is easier to route the signal to Fin* instead of Fin, then this is acceptable as well.

Product Folder Links: LMX2491



10.2 Layout Example

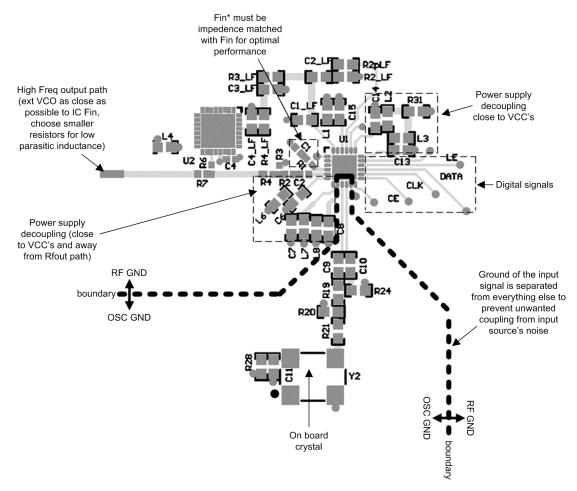


Figure 33. Layout Recommendation

Product Folder Links: LMX2491

Submit Documentation Feedback



11 Device and Documentation Support

11.1 Device Support

11.1.1 Development Support

Texas Instruments has several software tools to aid in the development process including TICS Pro for programming, PLLatinum Simulator Tool for loop filter design and phase noise/spur simulation. All these tools are available at www.ti.com.

11.2 Documentation Support

11.2.1 Related Documentation

For related documentation, see the following:

- AN-1879 Fractional N Frequency Synthesis (SNAA062)
- PLL Performance, Simulation, and Design

11.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.5 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

11.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.7 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Product Folder Links: LMX2491



PACKAGE OPTION ADDENDUM

11-Nov-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LMX2491RTWR	ACTIVE	WQFN	RTW	24	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	X2491	Samples
LMX2491RTWT	ACTIVE	WQFN	RTW	24	250	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	X2491	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

11-Nov-2016

n no event shall TI's liabilit	ty arising out of such informatio	n exceed the total purchase	price of the TI part(s	at issue in this document sold by	y TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 11-Nov-2016

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMX2491RTWR	WQFN	RTW	24	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LMX2491RTWT	WQFN	RTW	24	250	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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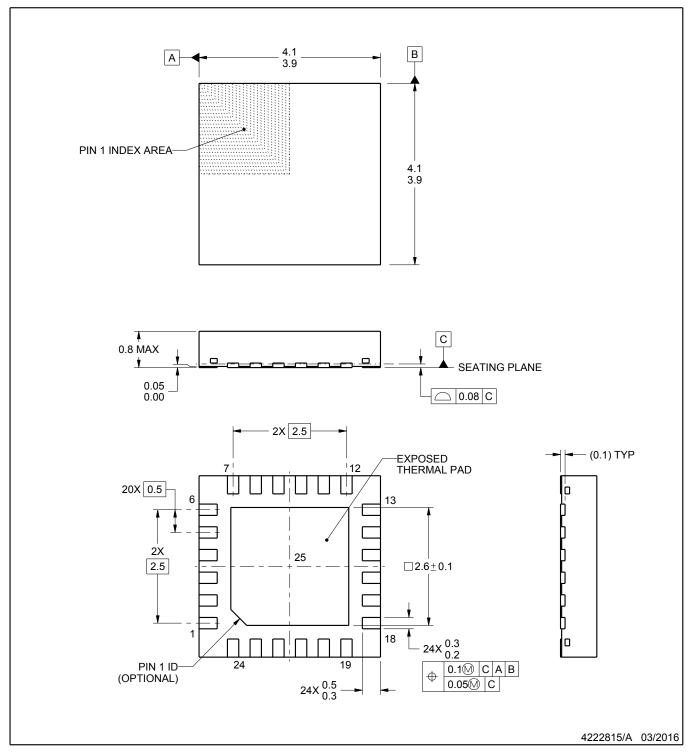


*All dimensions are nominal

Device	Package Type	e Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)	
LMX2491RTWR	WQFN	RTW	24	1000	210.0	185.0	35.0	
LMX2491RTWT	WQFN	RTW	24	250	210.0	185.0	35.0	



PLASTIC QUAD FLATPACK - NO LEAD

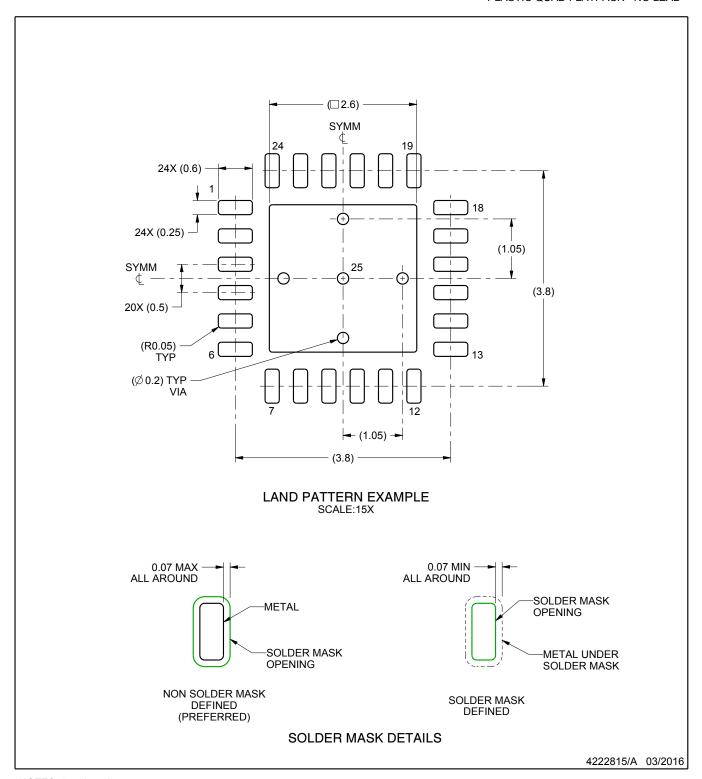


NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



PLASTIC QUAD FLATPACK - NO LEAD

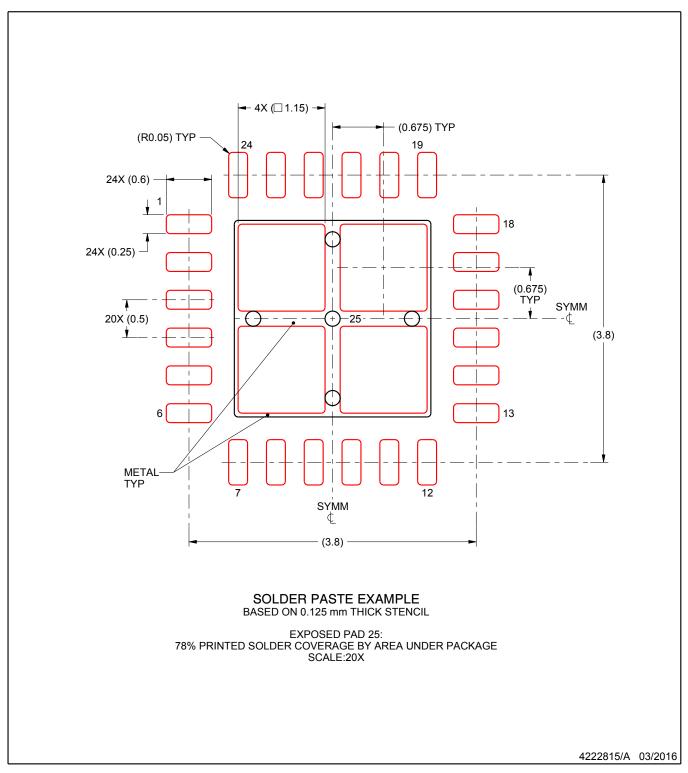


NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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